

LP-NSM075

Surface mount fuses

Features

- Very small size of 1206
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV



Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-NSM075	3.50	1.80	1.30	0.60	0.20

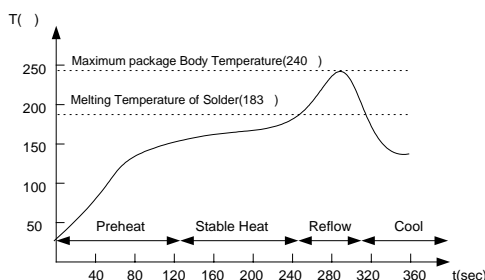
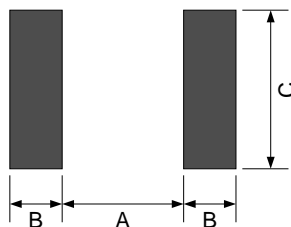


Electrical Characteristics

Part number	I _H	I _T	V _{max}	I _{max}	T _{trip}	P _{d typ}	R _{min}	R _{1max}	
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-NSM075	0.75	1.50	6	40	8.0	0.20	0.6	0.10	0.29

I_H=Hold current: maximum current at which the device will not trip at 25 °C still air.
 I_T=Trip current: minimum current at which the device will always trip at 25 °C still air.
 V_{max}=Maximum voltage device can withstand without damage at rated current.
 I_{max}=Maximum fault current device can withstand without damage at rated voltage.
 T_{trip}=Maximum time to trip(s) at assigned current.
 P_{d typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min}=Minimum device resistance at 25 °C prior to tripping.
 R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A	B	C
	(mm)	(mm)	(mm)
LP-NSM075	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 3000pcs per reel.